



PBSS4021PX-Q

20 V, 6.2 A PNP low V_{CEsat} transistor

3 July 2026

Product data sheet

1. General description

PNP low V_{CEsat} transistor in a medium power and flat lead SOT89 (SC-62) Surface-Mounted Device (SMD) plastic package.

NPN complement: PBSS4021NX-Q

2. Features and benefits

- Very low collector-emitter saturation voltage V_{CEsat}
- High collector current capability I_C and I_{CM}
- High collector current gain (h_{FE}) at high I_C
- High energy efficiency due to less heat generation
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Loadswitch
- Battery-driven devices
- Power management
- Charging circuits
- Power switches (e.g. motors, fans)

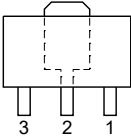
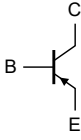
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CEO}	collector-emitter voltage	open base	-	-	-20	V
I _C	collector current		-	-	-6.2	A
I _{CM}	peak collector current	single pulse; t _p ≤ 1 ms	-	-	-15	A
R _{CEsat}	collector-emitter saturation resistance	I _C = -4 A; I _B = -400 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _{amb} = 25 °C	-	23	38	mΩ

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	E	emitter	 SOT89	 006aaa231
2	C	collector		
3	B	base		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBSS4021PX-Q	SOT89	plastic, surface-mounted package; 3 leads; 1.5 mm pitch; 4.5 mm x 2.5 mm x 1.5 mm body	SOT89

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
PBSS4021PX-Q	%6E

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CBO}	collector-base voltage	open emitter		-	-20	V
V _{CEO}	collector-emitter voltage	open base		-	-20	V
V _{EBO}	emitter-base voltage	open collector		-	-5	V
I _C	collector current			-	-6.2	A
I _{CM}	peak collector current	single pulse; t _p ≤ 1 ms		-	-15	A
I _B	base current			-	-1	A
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	600	mW
			[2]	-	1.5	W
			[3]	-	1.45	W
			[4]	-	2.45	W
			[5]	-	2.5	W
T _j	junction temperature			-	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided, 35 µm copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated, mounting pad for collector 6 cm².
- [3] Device mounted on an FR4 PCB, 4-layer, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, 4-layer, tin-plated, mounting pad for collector 1 cm².
- [5] Device mounted on a ceramic PCB, Al₂O₃, single-sided, 35 µm copper, tin-plated and standard footprint.

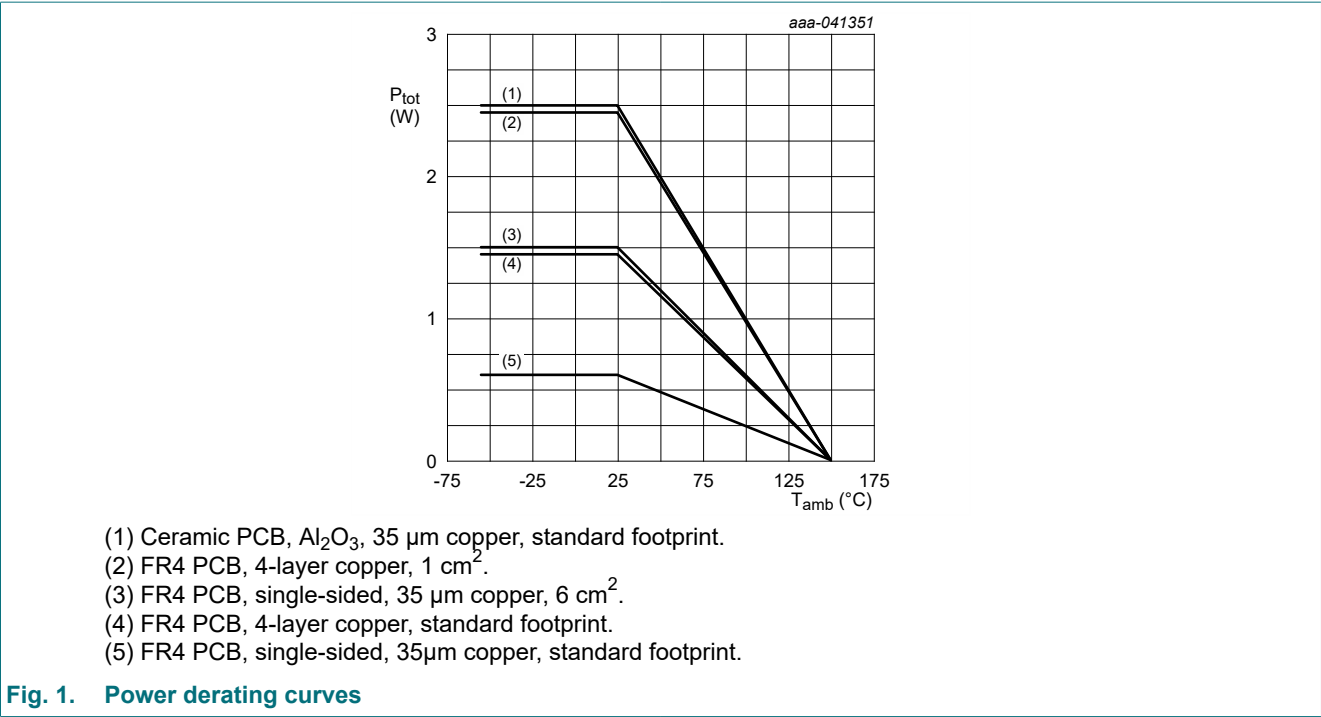


Fig. 1. Power derating curves

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	208	K/W
			[2]	-	-	83	K/W
			[3]	-	-	86	K/W
			[4]	-	-	51	K/W
			[5]	-	-	50	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	20	K/W

- [1] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated, mounting pad for collector 6 cm².
- [3] Device mounted on an FR4 PCB, 4-layer, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, 4-layer, tin-plated, mounting pad for collector 1 cm².
- [5] Device mounted on a ceramic PCB, Al₂O₃, single-sided, 35 µm copper, tin-plated and standard footprint.

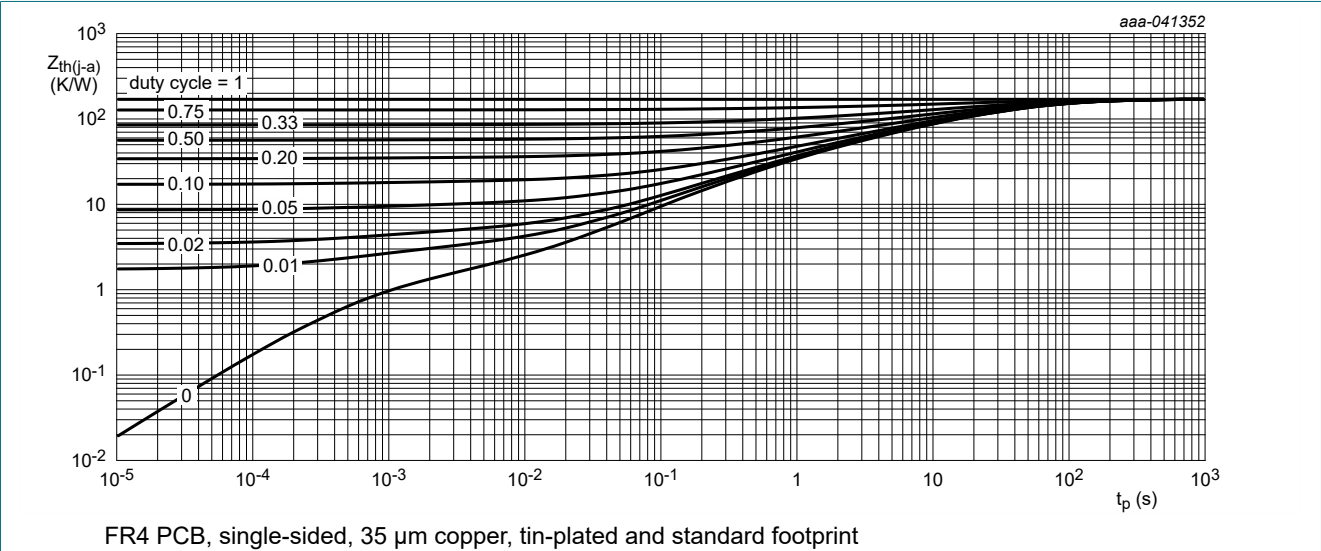


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

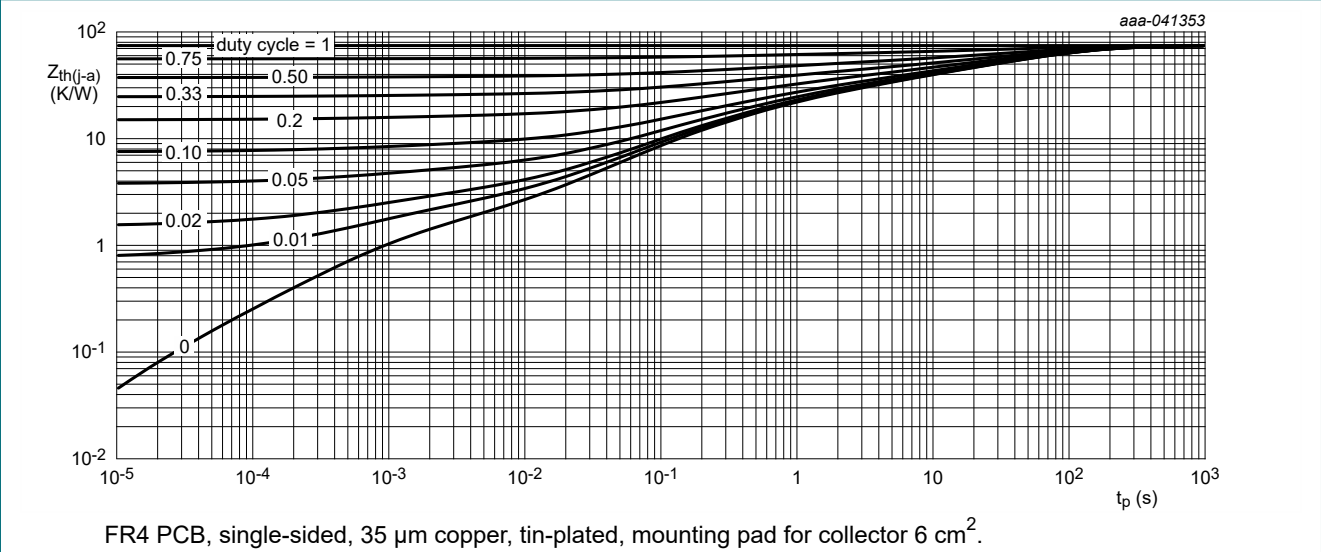
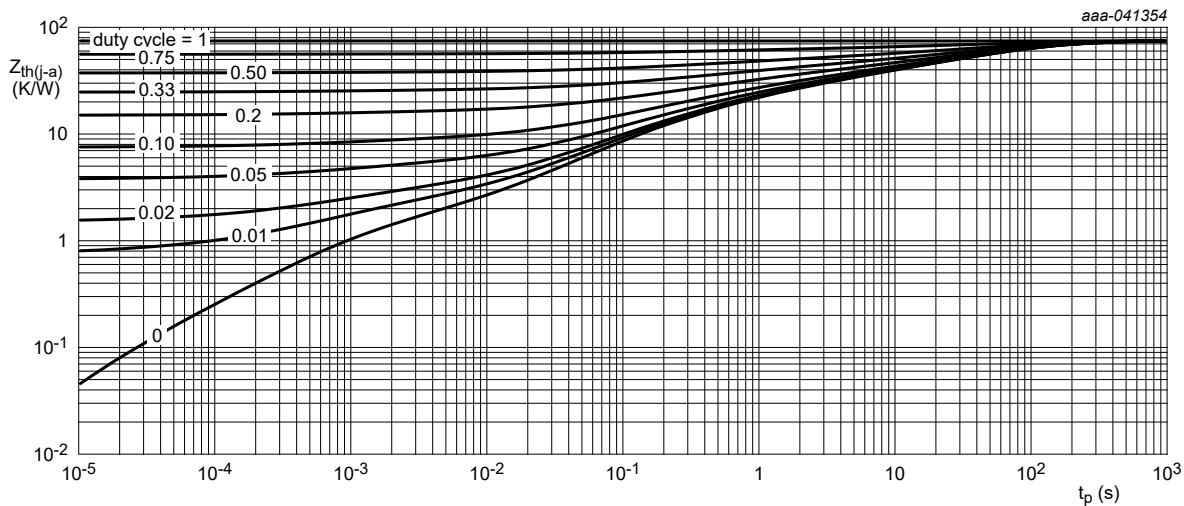
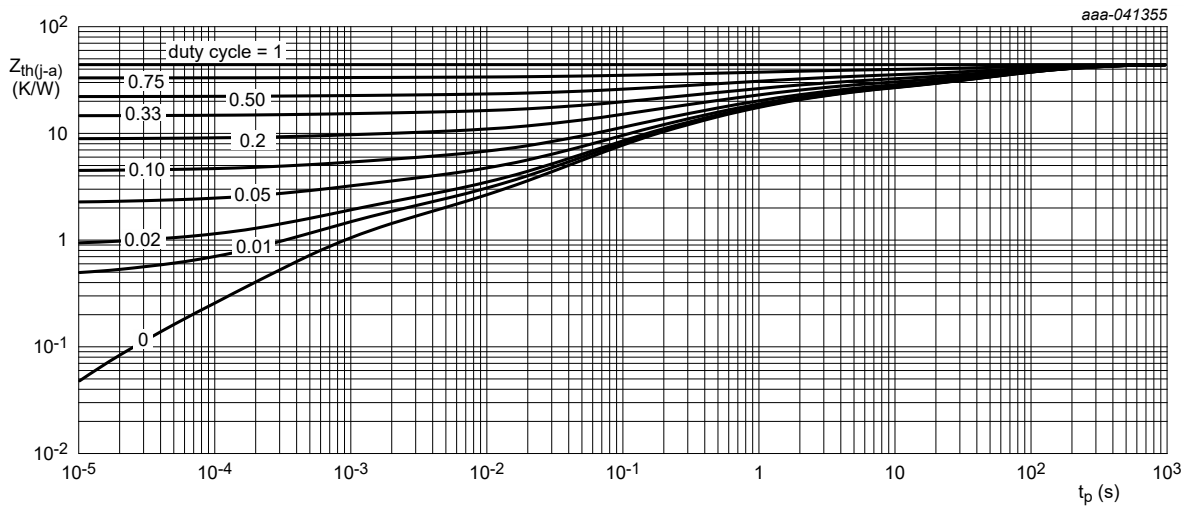


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



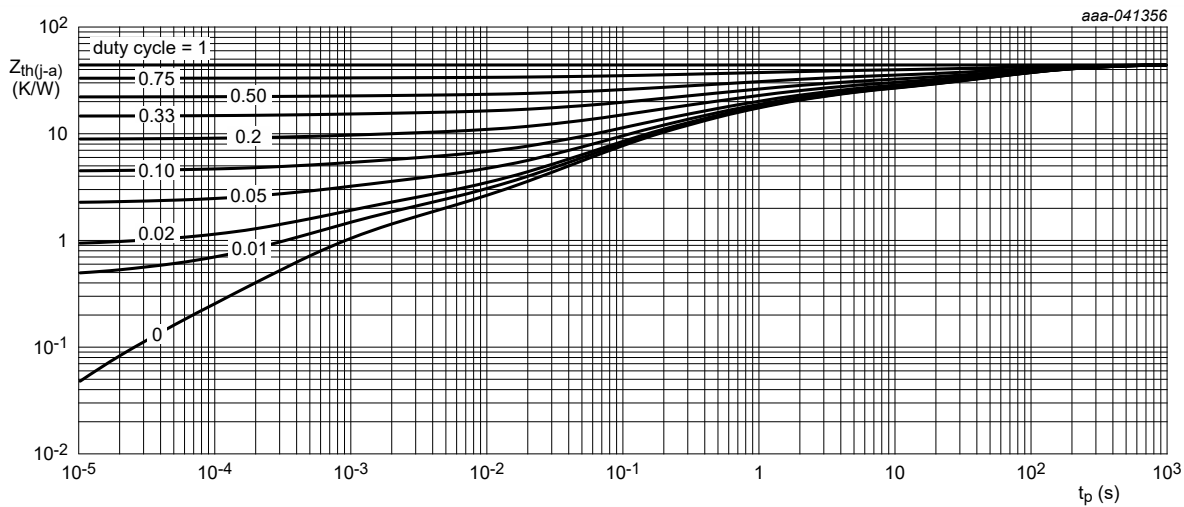
FR4 PCB, 4-layer 35 μ m copper, tin-plated and standard footprint.

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, 4-layer 35 μ m copper, tin-plated, mounting pad for collector 1 cm².

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al₂O₃, single-sided, 35 μ m copper, tin-plated and standard footprint.

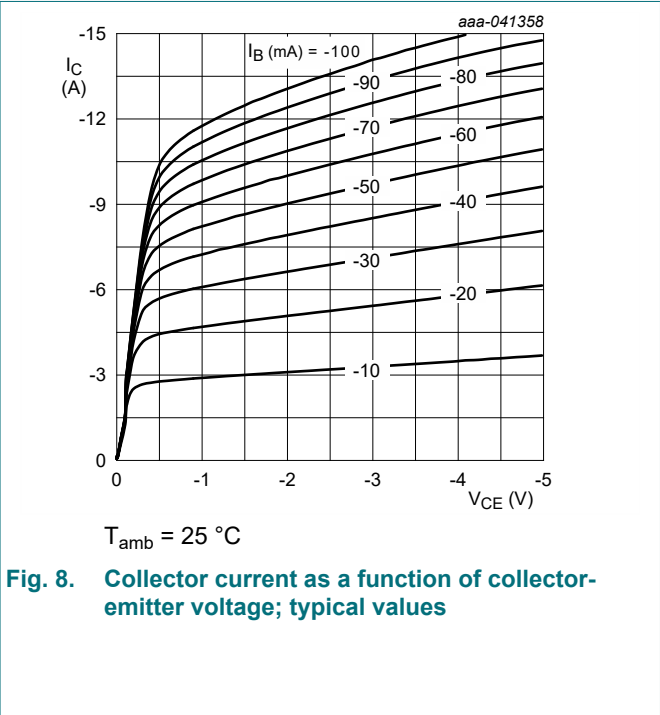
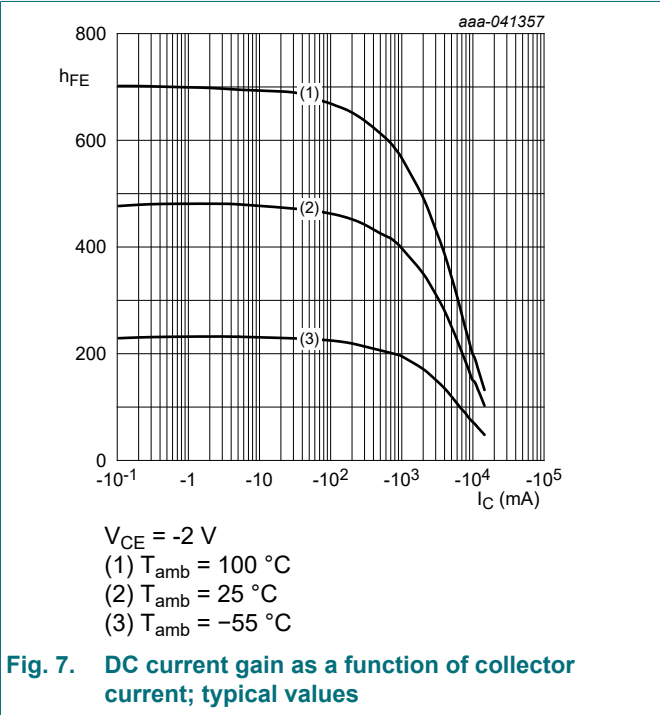
Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = -100\ \mu\text{A}$; $I_E = 0\ \text{A}$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-20	-	-	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	$I_C = -10\ \text{mA}$; $I_B = 0\ \text{A}$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-20	-	-	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	$I_E = -100\ \mu\text{A}$; $I_C = 0\ \text{A}$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-5	-	-	V
I_{CBO}	collector-base cut-off current	$V_{CB} = -20\ \text{V}$; $I_E = 0\ \text{A}$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-	-100	nA
		$V_{CB} = -20\ \text{V}$; $I_E = 0\ \text{A}$; $T_j = 150\ ^\circ\text{C}$	-	-	-50	μA
I_{CES}	collector-emitter cut-off current	$V_{CE} = -16\ \text{V}$; $V_{BE} = 0\ \text{V}$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-	-100	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\ \text{V}$; $I_C = 0\ \text{A}$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-	-100	nA
h_{FE}	DC current gain	$V_{CE} = -2\ \text{V}$; $I_C = -0.5\ \text{A}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	250	425	-	
		$V_{CE} = -2\ \text{V}$; $I_C = -1\ \text{A}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	250	405	-	
		$V_{CE} = -2\ \text{V}$; $I_C = -2\ \text{A}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	200	355	-	
		$V_{CE} = -2\ \text{V}$; $I_C = -4\ \text{A}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	150	290	-	
		$V_{CE} = -2\ \text{V}$; $I_C = -7\ \text{A}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	80	210	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -1\ \text{A}$; $I_B = -10\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-50	-90	mV
		$I_C = -1\ \text{A}$; $I_B = -50\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-30	-50	mV
		$I_C = -2\ \text{A}$; $I_B = -40\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-60	-110	mV
		$I_C = -4\ \text{A}$; $I_B = -40\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-130	-270	mV
		$I_C = -4\ \text{A}$; $I_B = -200\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-90	-160	mV
		$I_C = -6.9\ \text{A}$; $I_B = -345\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-160	-265	mV
R_{CEsat}	collector-emitter saturation resistance	$I_C = -4\ \text{A}$; $I_B = -400\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	23	38	m Ω
V_{BEsat}	base-emitter saturation voltage	$I_C = -1\ \text{A}$; $I_B = -100\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-0.82	-0.9	V
		$I_C = -4\ \text{A}$; $I_B = -400\ \text{mA}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-0.93	-1.05	V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = -2\ \text{V}$; $I_C = -2\ \text{A}$; pulsed; $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25\ ^\circ\text{C}$	-	-0.74	-0.85	V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_d	delay time	$V_{CC} = -12.5\text{ V}; I_C = -1\text{ A}; I_{B(on)} = -50\text{ mA};$ $I_{B(off)} = 50\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	43	-	ns
t_r	rise time		-	50	-	ns
t_{on}	turn-on time		-	93	-	ns
t_s	storage time		-	347	-	ns
t_f	fall time		-	87	-	ns
t_{off}	turn-off time		-	434	-	ns
f_T	transition frequency	$V_{CE} = -10\text{ V}; I_C = -100\text{ mA}; f = 100\text{ MHz};$ $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	91	-	MHz
C_c	collector capacitance	$V_{CB} = -10\text{ V}; I_E = 0\text{ A}; i_e = 0\text{ A};$ $f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	129	-	pF



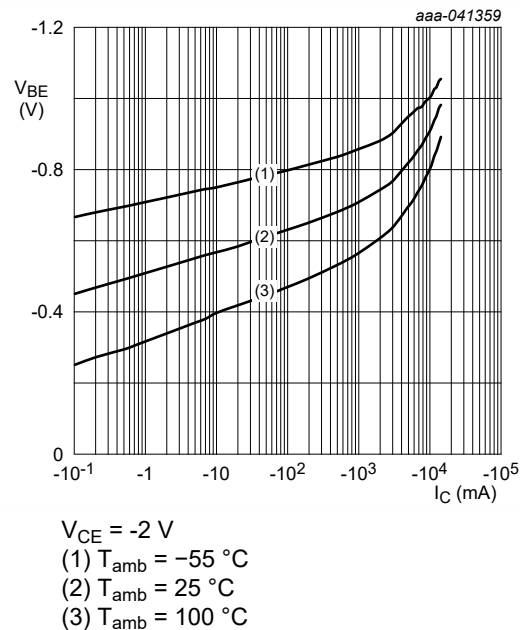


Fig. 9. Base-emitter voltage as a function of collector current; typical values

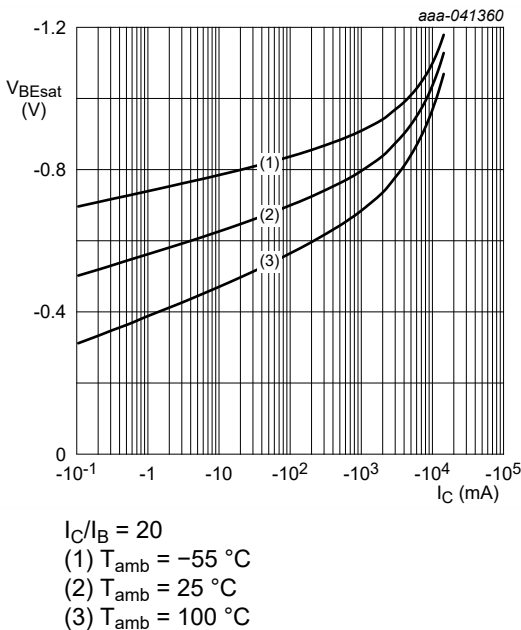


Fig. 10. Base-emitter saturation voltage as a function of collector current; typical values

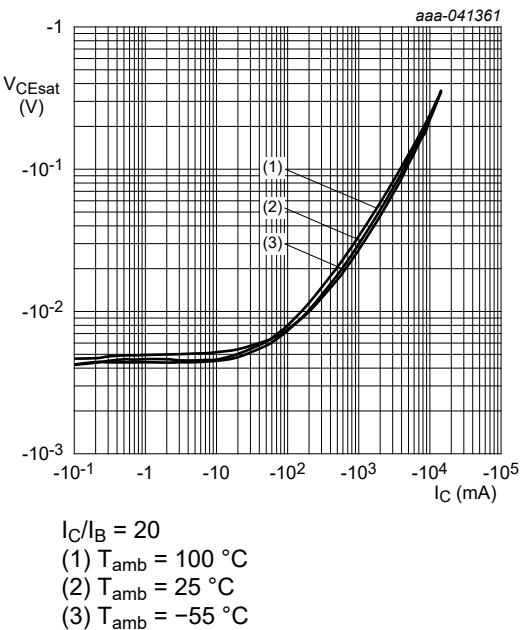


Fig. 11. Collector-emitter saturation voltage as a function of collector current; typical values

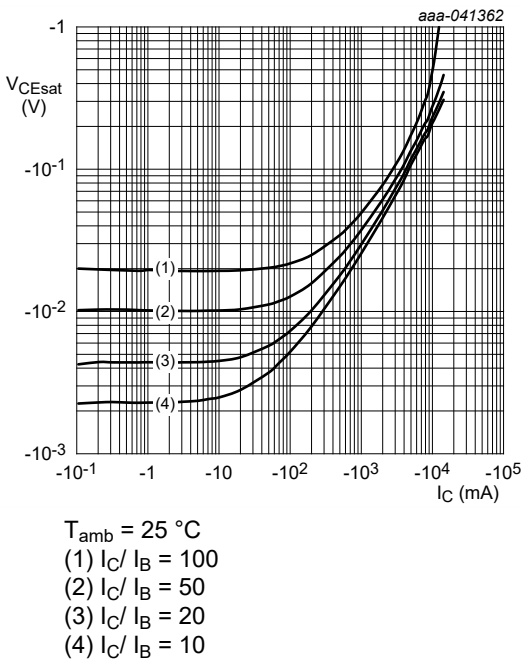


Fig. 12. Collector-emitter saturation voltage as a function of collector current; typical values

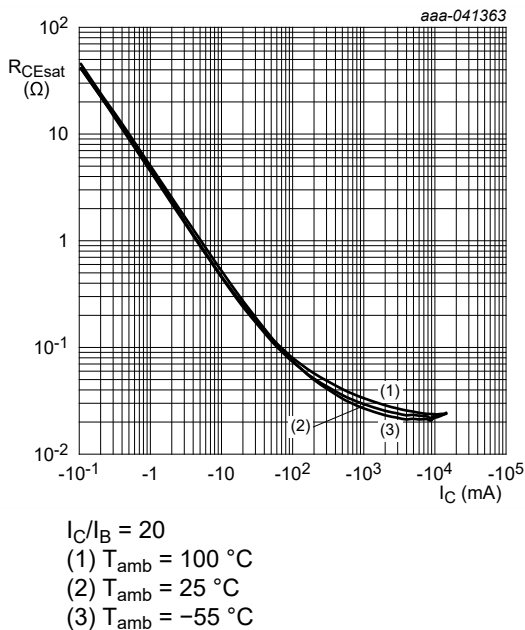


Fig. 13. Collector-emitter saturation resistance as a function of collector current; typical values

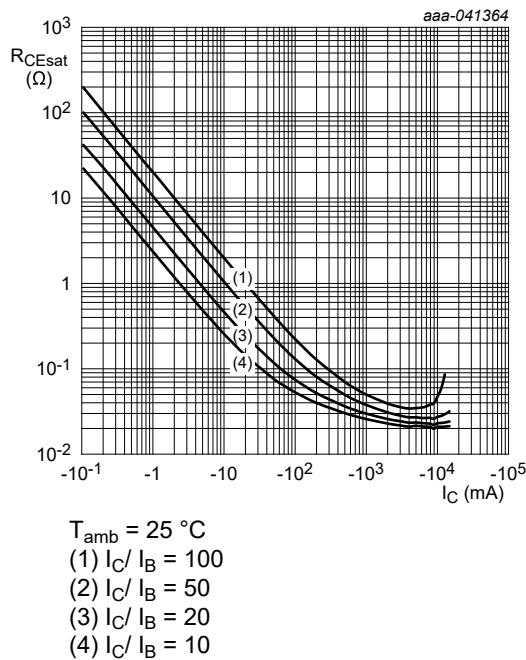


Fig. 14. Collector-emitter saturation resistance as a function of collector current; typical values

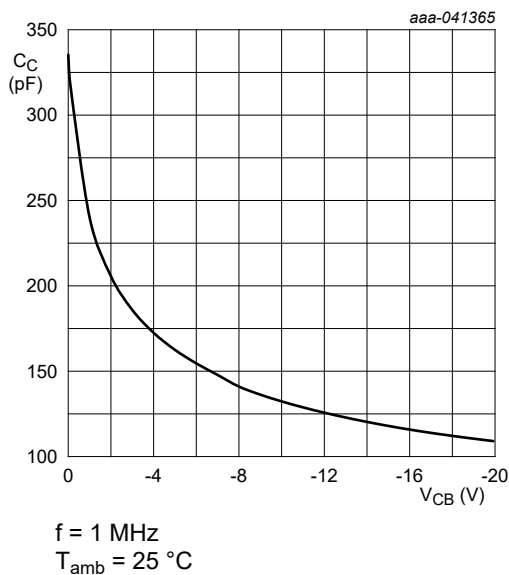


Fig. 15. Collector capacitance as a function of collector-base voltage; typical value

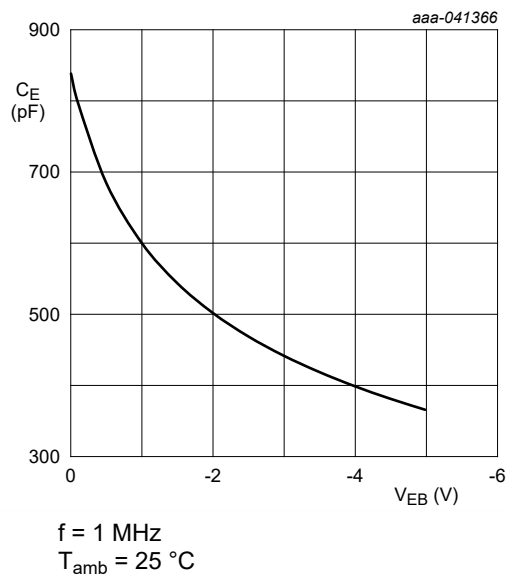


Fig. 16. Emitter capacitance as a function of emitter-base voltage; typical value

11. Test information

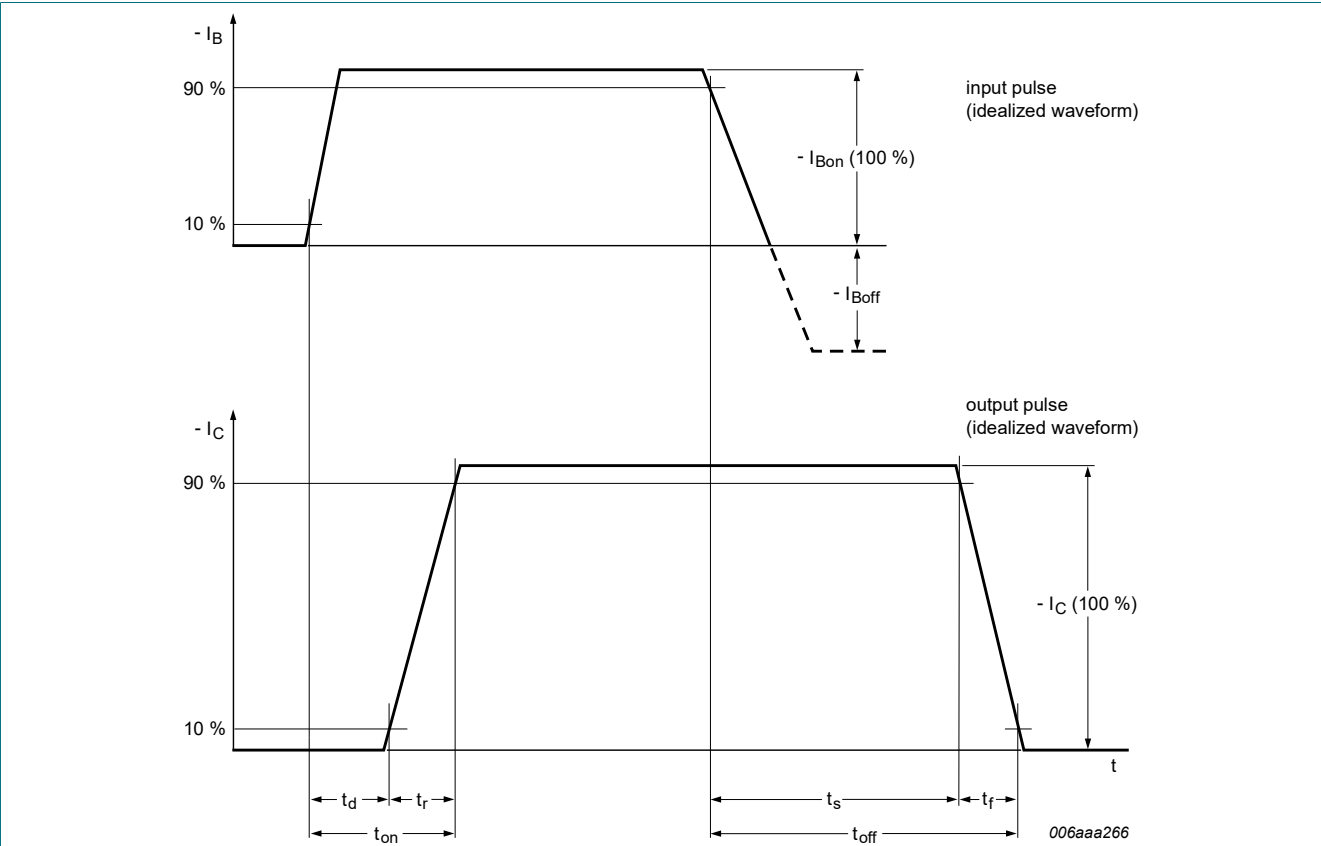


Fig. 17. Transistor switching time definition

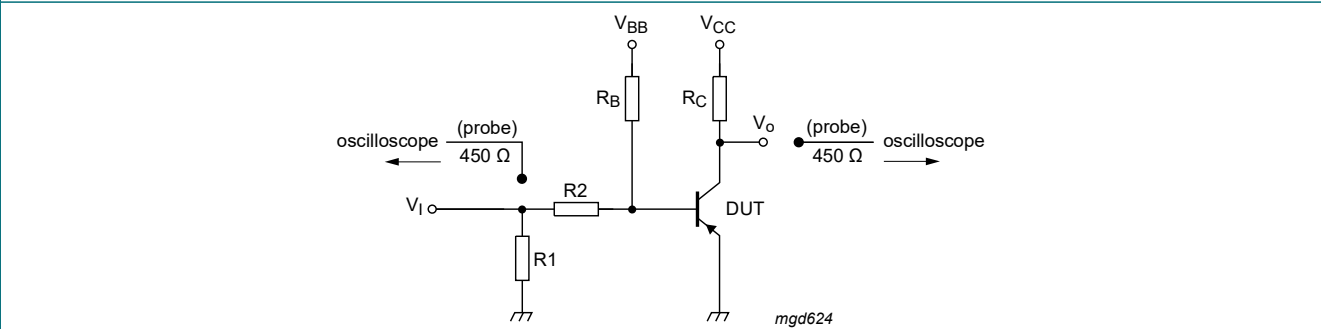
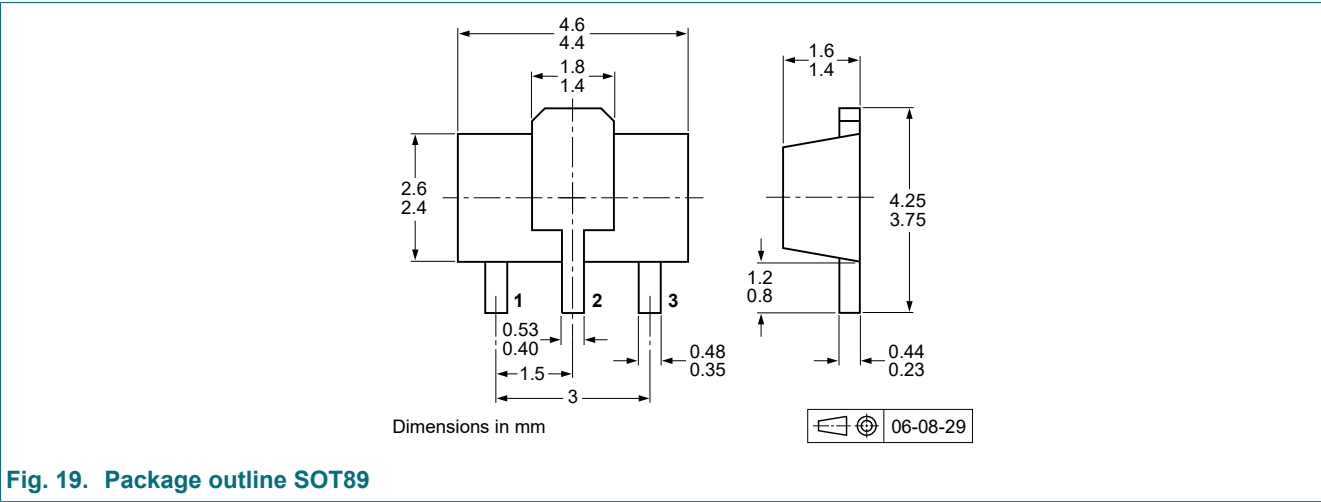


Fig. 18. Test circuit for switching times

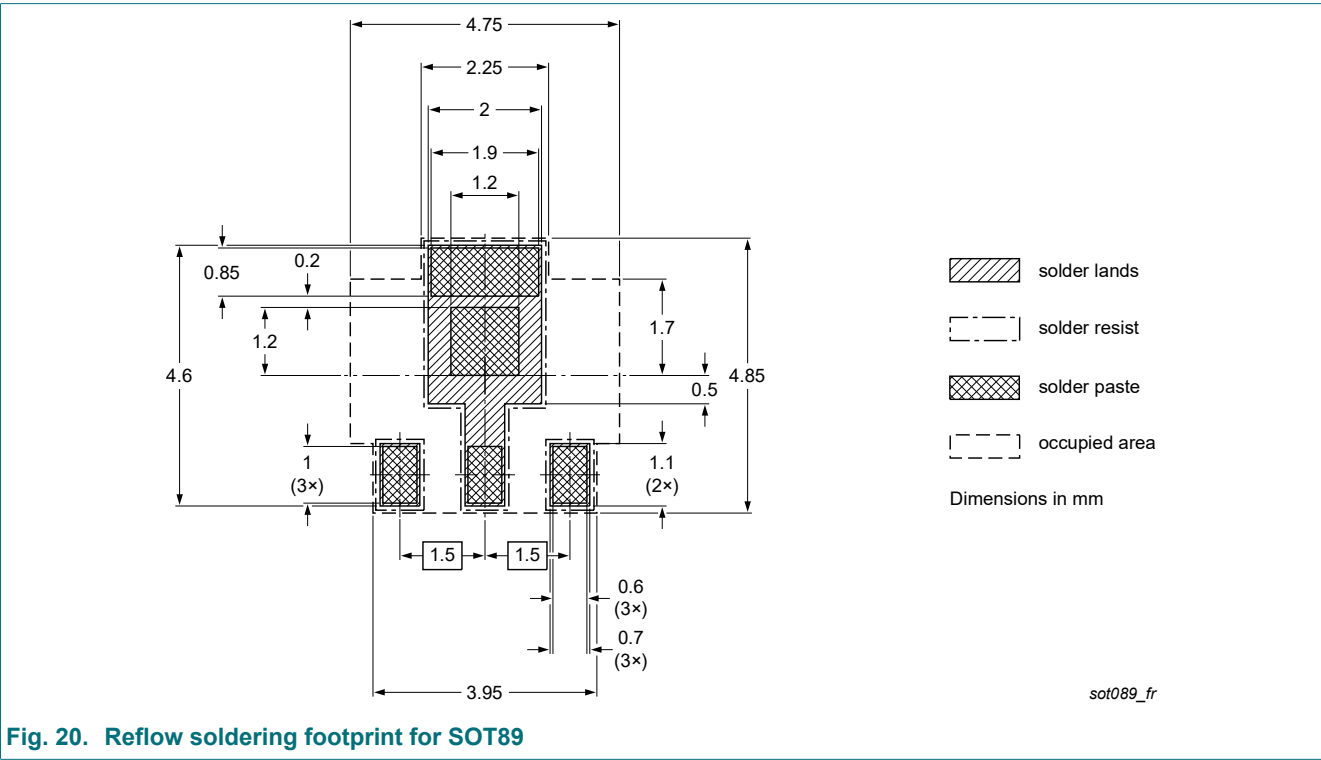
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline



13. Soldering



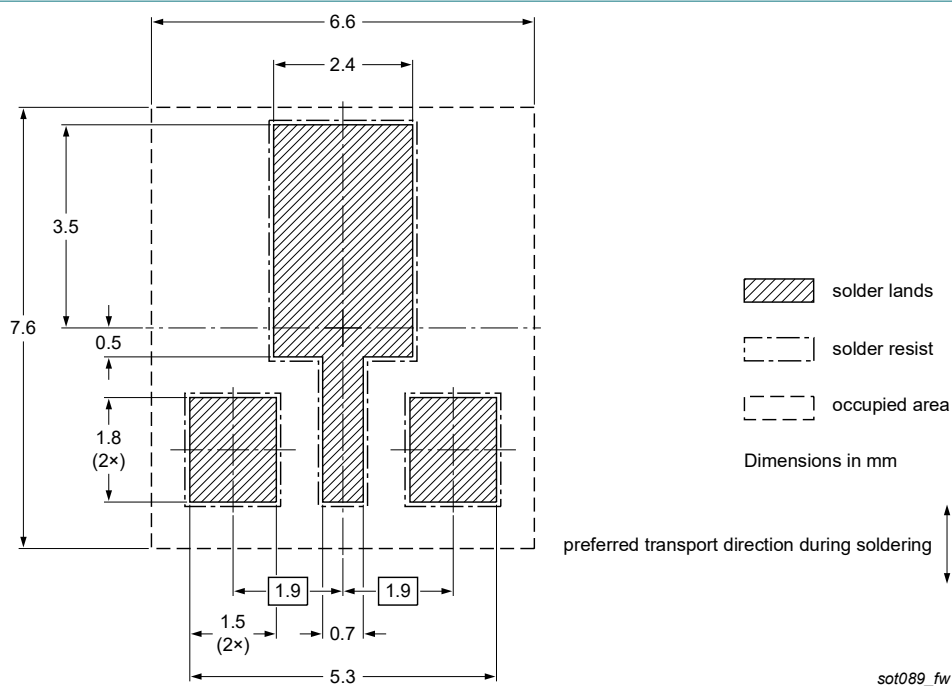


Fig. 21. Wave soldering footprint for SOT89

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBSS4021PX-Q v.3	20260703	Product data sheet	-	PBSS4021PX-Q v.2
Modifications:	• Thermal characteristics, Fig.1: Grid of graph corrected			
PBSS4021PX-Q v.2	20250109	Product data sheet	-	PBSS4021PX-Q v.1
PBSS4021PX-Q v.1	20240105	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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